Abstracts

Characterization of plated via hole fences for isolation between stripline circuits in LTCC packages

G.E. Ponchak, Donghoon Chen, Jong-Gwan Yook and L.P.B. Katehi. "Characterization of plated via hole fences for isolation between stripline circuits in LTCC packages." 1998 MTT-S International Microwave Symposium Digest 98.3 (1998 Vol. III [MWSYM]): 1831-1834.

Reduced coupling between adjacent striplines in LTCC packages is commonly accomplished by walls made of plated via holes. In this paper, a 3D-FEM electromagnetic simulation of stripline with filled via fences on both sides is presented. It is shown that the radiation loss of the stripline and the coupling between striplines increases if the fence is placed too close to the stripline.

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